

New approaches to increase the efficiency of the electromagnetic modeling of planar RF and microwave circuits

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Introduction: some challenges for planar solvers

- High-speed and RF circuits
 - quasi-static approximation
 - polygonal mesh
 - star-loop transformation
 - examples

Multidimensional Adaptive Parameter Sampling

- full-wave versus circuit analysis
- adaptive model building based on reflective exploration
- examples

Conclusion





- very large structures e.g. antenna arrays
- finite ground plane effects
- optimisation as a function of frequency and geometrical parameters e.g. in filter or antenna design
- thick conductors e.g. in on-chip interconnect
- geometrically complex structures with many ports
- real 3D features e. g. bonding wires or non-planar stratified substrates





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First challenge: high-speed and RF circuits





Challenging circuits

- high-speed digital RF board
- IC package (e.g. BGA)
- RF module (MCM, LTCC)
- RFIC (silicon)

Distinguishing features

- electrically small
- geometrically complex
- many ports
- from DC to RF





"Classical" circuits





Classical circuits

- microwave hybrid (Alumina)
- microwave MMIC (GaAs)
- planar antennas and arrays





Typical features

- order of wavelength dimensions
- geometrically simple
- few ports
- microwave and millimeter waves
- mixed strip-slot circuits

Mixed Potential Integral Equation

$$\begin{split} \mathbf{E}(\mathbf{J}_{S}) &= -j\omega\mathbf{A}(\mathbf{r}) - \frac{1}{j\omega}\nabla\Phi(\mathbf{r}) \\ \mathbf{A}(\mathbf{r}) &= \iint_{S}\overline{\mathbf{G}}^{A}(\mathbf{r} \mid \mathbf{r}') \cdot \mathbf{J}_{S}(\mathbf{r}')dS' \\ \Phi(\mathbf{r}) &= \iint_{S}\mathbf{G}^{\Phi}(\mathbf{r} \mid \mathbf{r}')(\nabla_{t}' \cdot \mathbf{J}_{S}(\mathbf{r}'))dS \end{split}$$

Method of Moments solution

- mixed triangle rectangle mesh
- introduction of rooftop basis functions to represent unknown surface currents









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Full-wave versus quasi-static





Distinguishing features

- electrically small
- geometrically complex
- many ports
- from DC to RF

- near-field / low frequency approximation
 - $L(\omega) = L_0 + \omega L_1 + \omega L_2 + \dots$
 - $C(\omega) = C_0 + \omega C_1 + \omega C_2 + \dots$



- L_0 and C_0 are frequency independent
- far-field radiation terms are neglected



D [mm]

Traditional meshing



Rectangular - triangular mesh at microwave frequencies







Rectangular - triangular mesh at RF frequencies



now the mesh is governed by the geometrical complexity

Introduction of arbitrary polygonal cells <u>and</u> corresponding current basis functions





Generalised basis functions

- generalisation of well-known rooftops on triangles and rectangles
- current is curl free
- the divergence is constant i.e. constant surface charge

$$\frac{\partial}{\partial x}J_{x} + \frac{\partial}{\partial y}J_{y} = A$$
$$\frac{\partial}{\partial y}J_{x} - \frac{\partial}{\partial x}J_{y} = 0$$



 $\mathbf{J} \cdot \mathbf{n} = 0$ on boundary c, except on red parts, where the value is either 0 or 1

Solution: solve an integral equation for a function K $J(\mathbf{r}) = \frac{A}{2}\mathbf{r} + \nabla K \quad (K \text{ is a harmonic function})$ $\frac{\partial}{\partial n}K = \begin{cases} 0 & -\frac{A}{2}\mathbf{r} \cdot \mathbf{n} \end{cases}$



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Optimised polygonal mesh





Distinguishing features

- electrically small
- geometrically complex
- many ports
- from DC to RF

- minimizes number of cells, respecting $\lambda/10$ criterion
- handles geometrical complexity
- extends well-known concepts for triangles and rectangles





Method of Moments [Z].[I]=[V] $[Z] = j\omega[L] + 1/j\omega [C]^{-1}$

for low frequences: zero infinity

[Z] is ill-conditioned for low frequencies

⇒ numerical solution breaks down

solution: the star-loop transformation



Distinguishing features

- electrically small
- geometrically complex
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The star-loop transformation



- original basis functions: rooftops
- these basis functions are now transformed into a new set of basis functions: the loop functions and the star functions
- this transform is linear







High Speed Digital and Analog RF Applications





Some sample applications



Example 1: RF board interconnect





Rule of thumb: frequency < 2.66 GHz





Classical (Momentum) mesh: 20 cells/λ at 1 GHz Matrix size : 3428 Process size : 152.48 MB User time : 3h 14m 51s



rectangular and triangular mesh







polygonal mesh

Memory saving: factor 3 CPU-time saving: factor 14



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Example 1: RF board interconnect - cont.







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Example 2: ball grid array package



Rule of thumb: frequency < 2.66 GHz

Purpose: time-domain analysis for a 100ps rise time signal and 50Ω loads



Example 2: ball grid array package - cont.



classical (Momentum)

Matrix size	1	8244
Process size	:	> 1 GB
User time	:	> 1 day

new (Momentum RF)

Matrix size Process size : 106.6 MB

: 1354

- User time : 1h 47m 53s



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Field Analysis

- numerical solution of Maxwell's equations (finite elements; finite differences in time domain; method of moment solution of an integral equation)
- no partitioning complete circuit as a whole
- all high frequency couplings and radiation effects are included
- very accurate
- "slow": very CPU-time and memory demanding
- less suited for design, optimisation and tolerance analysis



Field analysis versus circuit analysis - cont.

Circuit Analysis

- based on Kirchoff laws
- structure is first partitioned into subcircuits
- parameterised models of (a class of) substructures are available
- fast and suited for design and optimisation
- many models of substructures are not very accurate
- the set of available models is limited (e.g. a tee, a stepin-width, an open end, ...)
- coupling between substructures and radiation is neglected



Field analysis versus circuit analysis - cont.





Method of Moment meshing of a low pass filter





Multidimensional Adaptive Parameter Sampling





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Existing approaches and techniques

- hand-made analytical models
- discrete model library
- Iook-up tables combined with local curve fitting
- artificial neural networks

Common drawbacks

- oversampling / undersampling
- inability to automatically control the accuracy



What are we looking for?

- fully automated algorithm
- no a-priori knowledge required
- minimum number of samples
- guaranteed and predefined accuracy
- highly adaptive
 - adaptive model building
 - adaptive sample selection in both frequency and parameter space
- samples: full wave MoM simulations
- obtained model: S-parameter or RLGC circuit model







data(*f*, **p**) =
$$\sum_{m} \{C_{m}(f) P_{m}(p)\}$$

- data: S-parameters or transmission line parameters (RLGC)
- f: frequency
- p: coordinates in parameter space
- P_m: orthonormal multidimensional polynomials (generalized Forsythe multinomials) (stored in database)
- C_m: frequency dependent fitting coefficients (stored in database)



Flow chart of up-front calculation





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Data selection for very costly data **Reflective exploration at multiple frequencies** start with initial set of data points new data points are selected based on reflective functions, e.g. difference between models of different order. check: | model1 - model2 | < accuracy level extrema: add samples near local minimum/maximum physical conditions: no gain allowed, check radiation



Example 1: open end





W: 20 μ m \rightarrow 120 μ m freq.: 0 \rightarrow 60 GHz accuracy: -60 dB







Example 2: gap coupling





$$\begin{split} \mathsf{S}(\mathsf{W},\mathsf{G},\mathsf{f}) &= \mathsf{C}_{\mathsf{o}}(\mathsf{f}) + \mathsf{C}_{\mathsf{1}}(\mathsf{f}) \; \mathsf{W} + \mathsf{C}_{\mathsf{2}}(\mathsf{f}) \; \mathsf{G} + \\ \mathsf{C}_{\mathsf{3}}(\mathsf{f}) \; \mathsf{W}\mathsf{G} + \ldots \; \mathsf{C}_{\mathsf{26}}(\mathsf{f}) \; \mathsf{W}^{\mathsf{4}}\mathsf{G} \end{split}$$



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Example 3: low pass filter





Method of Moments

circuit partitioning + MAPS

$$\epsilon_r$$
 = 10, tg δ = 0.015

635 μm



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Example 3: low pass filter - cont.





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Microstrip-fed patch antenna @ 10GHz - cont.





frequency (GHz)

- some couplings are neglected
- differences between model parameters and actual material and geometry data



frequency (GHz)

- optimised for 10 GHz center frequency
- takes only a few minutes of CPU-time!





- Image: Second state of the second state of
- If ull-wave analysis accuracy and flexibility and fast circuit analysis, design and optimisation can now be combined





